#### 简报

新型可返工环氧底部填充料的合成和性能

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收稿日期 2005-6-15 修回日期 2005-7-27 网络版发布日期 2006-4-25 接受日期

摘要 合成了两种分别含有叔酯键和叔醚键的环氧化合物EP-1和EP-2,其结构通过红外光谱、 氢核磁共振谱及环氧当量测定等方法得到证实。EP-1与已有商品ERL-4221以环氧物质的量比1:1 混合组成EP-3。EP-2和EP-3用酸酐类固化剂HMPA固化。TGA测试表明它们具有理想的起始热分解温度 (IDT=210~220℃),显著低于现在普遍应用的环氧底部填充料ERL-4221

(IDT=310℃)。它们的粘结强度和玻璃化转变温度 $T_g$ 在返工温度(225℃)老化数分钟后迅速降低,可以满足当前微电子倒装芯片封装对可返修工艺的要求。

关键词 可返工 底部填充料 环氧树脂 倒装芯片 热降解

分类号 TB34 TQ436

# Synthesis and properties of novel controlled thermally degradable epoxy resin for electronic packaging

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**Abstract** The synthesis, formulation and characterizations of two new diepoxides were reported, one diepoxide contains tertiary ester (EP-1) and the other contains tertiary ether linkages (EP-2). Both compounds were characterized with 1H-NMR and FT-IR and formulated into underfill materials with an anhydride as hardener and a 2-methylimidazole as catalyst. A dual-epoxy system (EP-3) was also formulated with the tertiary ester diepoxide and a conventional aliphatic diepoxide, ERL-4221, using the same hardener and catalyst. The thermogravimetric analysis (TGA) reveals that the cured EP-2 and EP-3 had obviously lower thermal decomposition onset temperature (around 215  $^{\circ}$ C) than ERL-4221 (310  $^{\circ}$ C). The shear strength and glass transition temperatures of these novel diepoxides decreas quickly upon being aged at 225  $^{\circ}$ C. The unusual thermal degradable properties make these compounds a potential use as reworkable underfill for flip-chip application.

Key words reworkable underfill materials diepoxide flip-chip thermal degradation

DOI:

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